

ABSTRACT

The present disclosure provides a data collection method, a data collection device, and a data collection system of the semiconductor processing equipment. The method includes receiving an activated data collection plan via the first communication interface (801), determining equipment data information to be collected in the data collection plan (802), sending the equipment data information to the semiconductor processing equipment via the second communication interface (803), and receiving equipment data corresponding to the equipment data information sent by the semiconductor processing equipment and forwarding the equipment data to the equipment control system via the first communication interface to display the equipment data (804).

FIG. 8